


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 06 December 2016 [Approved on 17 November 2025, 12:49 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.33%	TITANIUM	7440-32-6	0.1%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	0.6%
			SILVER, ELEMENTAL	7440-22-4	2.4%
			Silicon	7440-21-3	96.9%
Die attach	Lead and Lead alloys	0.77%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	15.32%	Carbon black	1333-86-4	0.4%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	1%
			Phenol, 4,4'-(1-methylethylidene)bis[2,6-dibromo-, polymer with (chloromethyl)oxirane Exempt from other regulatory requirements	40039-93-8	1%
			Phenol, polymer with formaldehyde	9003-35-4	6.5%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadfinish Leadframe	Tin plating	1.32%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	13%
			Fused Silica	60676-86-0	15%
			Quartz (SiO ₂)	14808-60-7	63.1%
			Tin	7440-31-5	100%
	Copper (e.g. copper amounts in cable harnesses)	82.26%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-41 (ZM) nHF	Diode axial	0.272	g